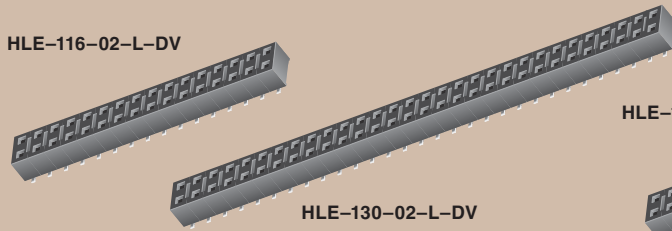
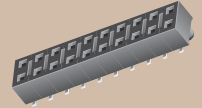


HLE-116-02-L-DV



HLE-110-02-L-DV-A



HLE-130-02-L-DV

.025"sq SOCKET HLE SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HLE

Insulator Material:

Black Liquid

Crystal Polymer

Contact Material:

BeCu

Plating:

Au over 50µ" (1,27µm) Ni

Current Rating:

2.5A @ 80°C ambient

Operating Temp Range:

-55°C to +125°C

Insertion Depth:

(1,78mm) .070" to (3,43mm) .135", pass-through, or (2,59mm) .102" min for bottom entry

Insertion Force:

(Single contact only)

2oz (0,56N) avg.

Withdrawal Force:

(Single contact only)

1.6oz (0,44N) avg.

RoHS Compliant:

Yes

Processing:

Max Processing Temp:

230°C for 60 seconds, or

260°C for 20 seconds 3x

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10mm) .004" max (02-20)

(0,15mm) .006" max (21-50)

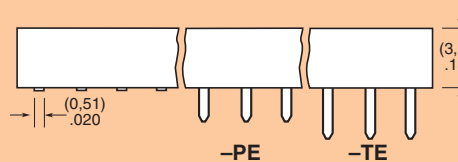
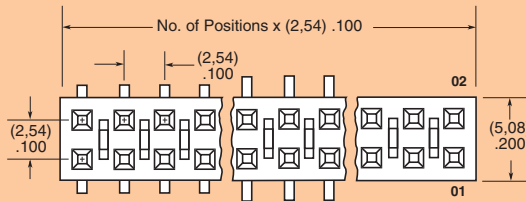


Mates With:

TSW, MTSW, DW, EW, ZW, TLW, TSM, MTLW, HW



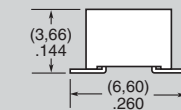
02 thru 50



-L
= 10µ" (0,25µm)
Gold on contact,
Gold Flash on tail

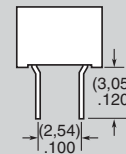
Note: Other Gold plating options available. Contact Samtec.

Leave blank for
Surface Mount

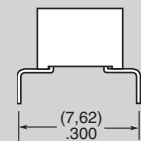


(Requires -BE for Bottom Entry)

-TE
= Through-Hole
Top Entry



-PE
= Through-hole
Pass Through Entry

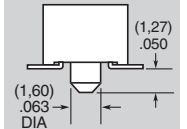


(Requires -BE for Bottom Entry)

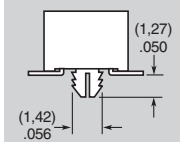
**OTHER
OPTION**

-BE
= Bottom Entry
(Requires Surface
Mount or -PE)

-A
= Alignment Pin
(4 positions min.)
Metal or plastic at
Samtec discretion
(N/A with -LC)

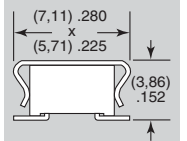


-LC
= Locking Clip
(2 positions min.)
(N/A with -A)



-K
= (6,50mm) .256"
DIA Polyimide
Film Pick &
Place Pad
(3 positions min.)
Not available
with -TE or
-PE tail option

-P
= Metal Pick &
Place Pad
(3 positions min.)



-TR
= Tape & Reel
Packaging
(29 positions max.)

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM